

BB02-CY :- 1.27mm (0.05") STRAIGHT SMD FEMALE HEADER, SINGLE ROW - 2 TO 40 CONTACTS, DUAL ENTRY

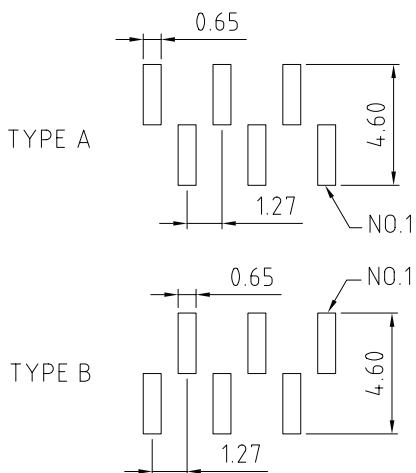
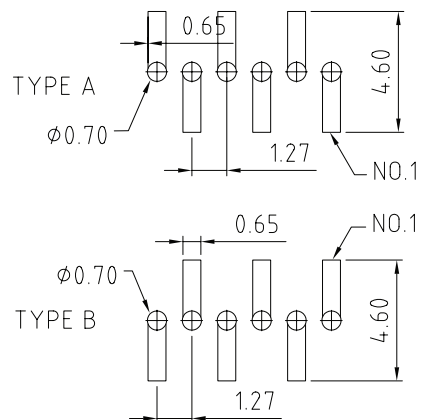
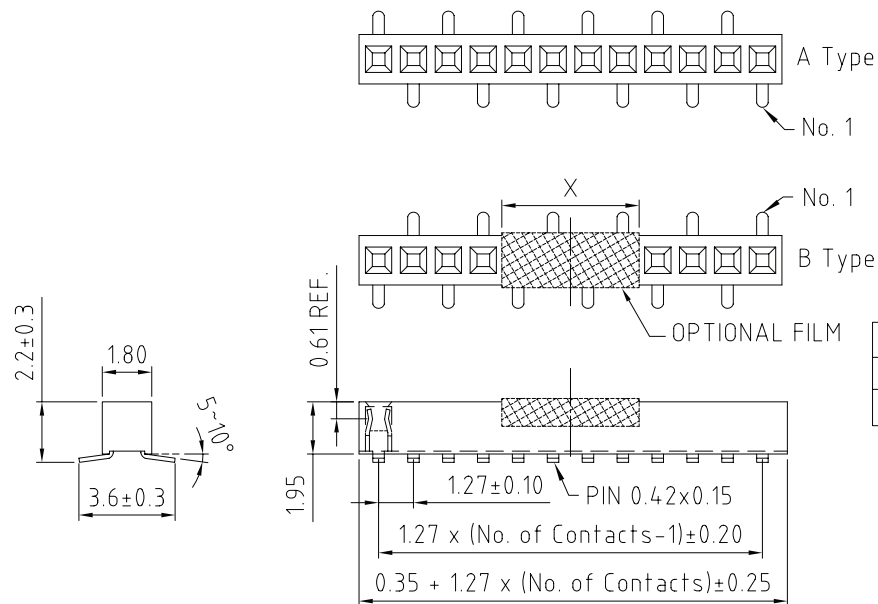
SPECIFICATIONS

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
DIELECTRIC WITHSTANDING	300 V AC/DC
CONTACT RESISTANCE	20m OHMS MAX.
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	POLYESTER UL 94V-0
	STANDARD NYLON 6T
PLATING	GOLD OR TIN OVER 30~50U" NICKEL
SOLDERABILITY	IR REFLOW: 260°C FOR 10 SEC
	WAVE: 230°C FOR 5-10 SEC
	MANNUAL SOLDER: 350°C FOR 3-5 SEC

NOTES:

1. RECOMMENDED MATING PIN LENGTH FOR TOP ENTRY: 1.5MM. $\triangle \triangle$

MATES WITH: - (0.40MM SQUARE PINS)

 $\triangle \triangle$ BB02-NA
BB02-NB
BB02-NCRECOMMENDED PCB LAYOUT FOR TOP ENTRY
(TOLERANCE: ± 0.05)RECOMMENDED PCB LAYOUT FOR BOTTOM ENTRY
(TOLERANCE: ± 0.05)

X	PIN NO.
5mm	02-25pins
10mm	26-40pins

HOW TO ORDER

B B 0 2 - C Y X X 2 - X X X - 0 0 0 0 0 0

NO. OF CONTACTS
02 TO 40CONTACT PLATING OPTIONS $\triangle$
K = GOLD FLASH (STANDARD)
A = 10U" GOLD ON CONTACT/GOLD FLASH ON TAIL
B = 15U" GOLD ON CONTACT/GOLD FLASH ON TAIL
C = 30U" GOLD ON CONTACT/GOLD FLASH ON TAIL
T = BRIGHT TIN
M = MATT TINFOOTPRINT TYPE
A = A TYPE
B = B TYPEPACKAGING OPTIONS
3 - TUBE
4 - TUBE & FILM
6 - T & R
7 - T & R & FILM

REV. DATE & DRN
10 20/07/06 - NYW RELEASE
11 24/07/06 - NYW DRAWING MODIFICATION
12 09/05/07 - NYW ADD BOTTOM ENTRY LAYOUT
13 16/07/07 - CHC CHANGE FROM GOLD CONTACT PLATING
14 05/05/08 - CHC AMEND MATES WITH
15 29/12/08 - CHC DRAWING MODIFICATION
16 20/08/09 - CHC AMEND MATIN PART
AMEND NOTES 1.

Scale: 5:1	THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10	Material SEE NOTE
Drawn: CHC			
App'd: XXXX	Title SOCKET		NOT TO SCALE
Date: 20 AUG '09	Revision: 1.6		UNIT: mm

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Type: BB02-CY

BB02-CY

Drawing Number:

Sheet 1 of 1

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